XINGLIGHT®

Part No. [illegible]-2520UOC/T

XI[illegible]520UOC/T

技术数据表

2520 橙光 直插[illegible]

特[illegible]（ ）：

L/W/H :2.1*2.3*2.6*Ø1.8mm

Appearance dimension (L / w / h): 2.1*2.3*[illegible]

: %W / : DW

Luminous color and colloid: Orange [illegible] /Water colloid

ROHS ñÈ

Environmental [illegible]tectio

rtiWaterp

电性参数

		-20 ~ +85 C	
		-40 ~ +85 C	
Welding conditions	Tsol	reflow soldering 240°C 6s manual welding 300°C 3s 2.0mm	

[redacted]

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代码	最小值	最大值	[redacted]	测试条件
A8	900	1200	mcd	IF=20mA
A9	1200	1500		
B1	1500	1800		
B2	1800	2100		

电压分档

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代码	最小值	最大值	单位	测试条件
N12-7	1.8	2.0	V	IF=20mA
N12-8	2.0	2.2		
N12-9	2.2	2.4		

[redacted]

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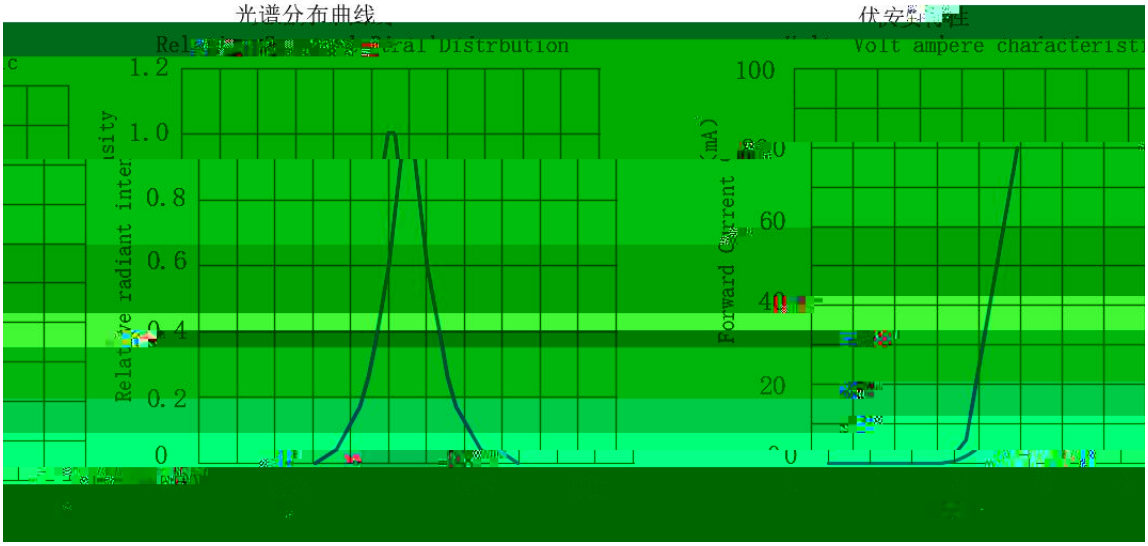
代码	最小值	最大值	单位	[redacted]
HO01	600	602.5	nm	IF=20mA
HO02	602.5	605		
HO03	605	607.5		
HO04	607.5	610		

典型特性曲线

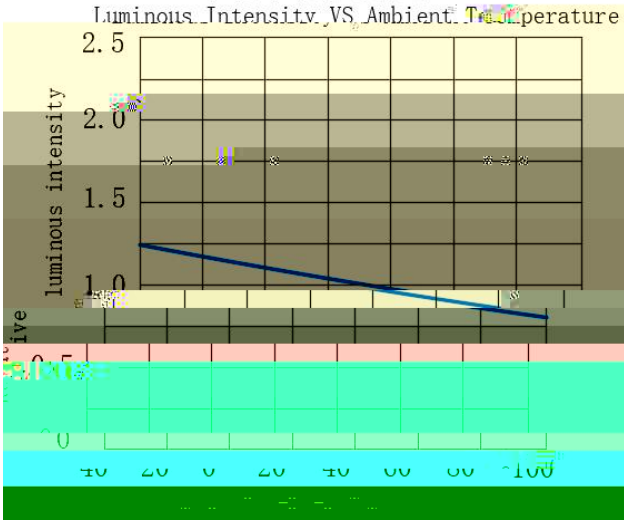
光谱分布曲线



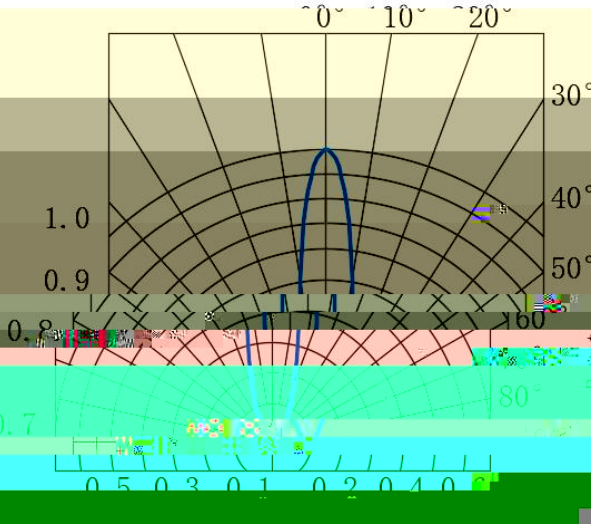
正向电流降额曲线

相对光强与正向电流特性

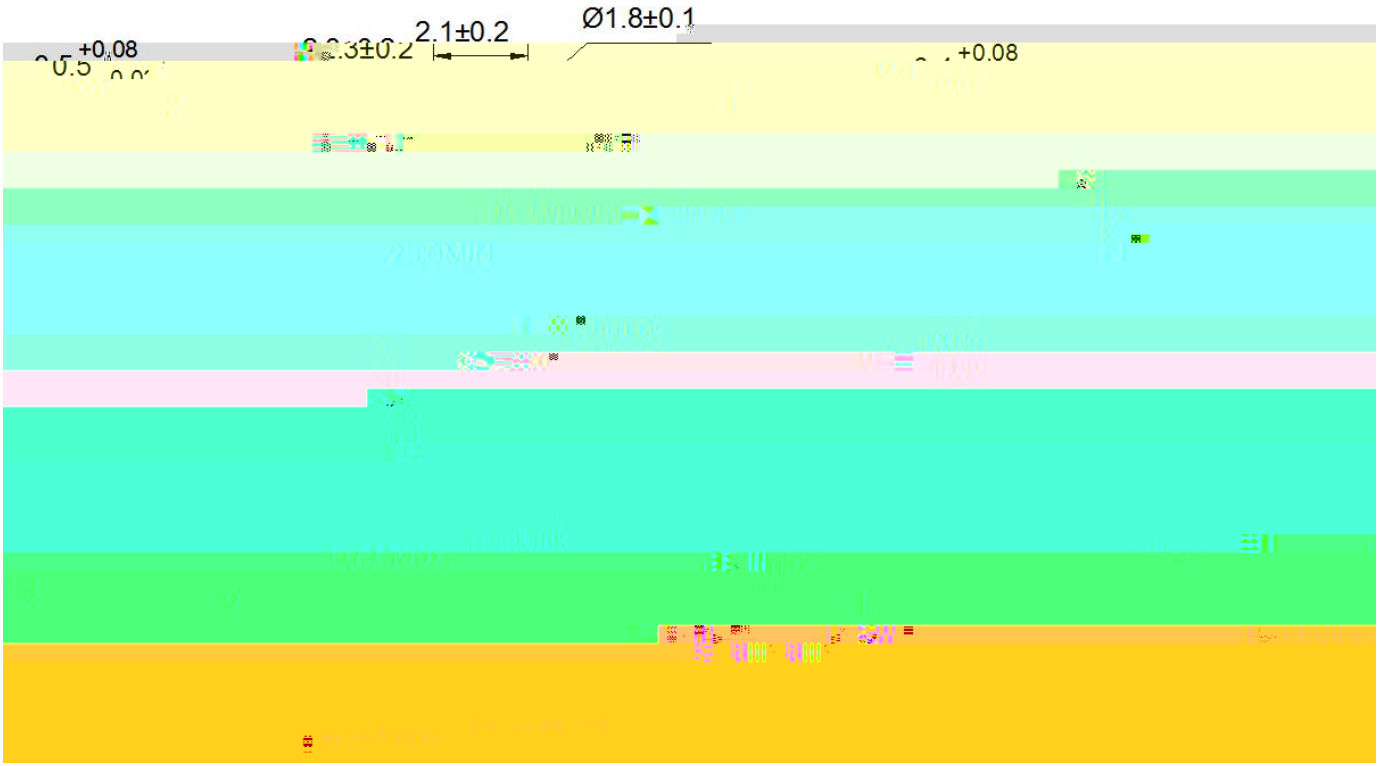
光强与环境温度曲线



相对辐射强度与空间角度关系



外形尺寸

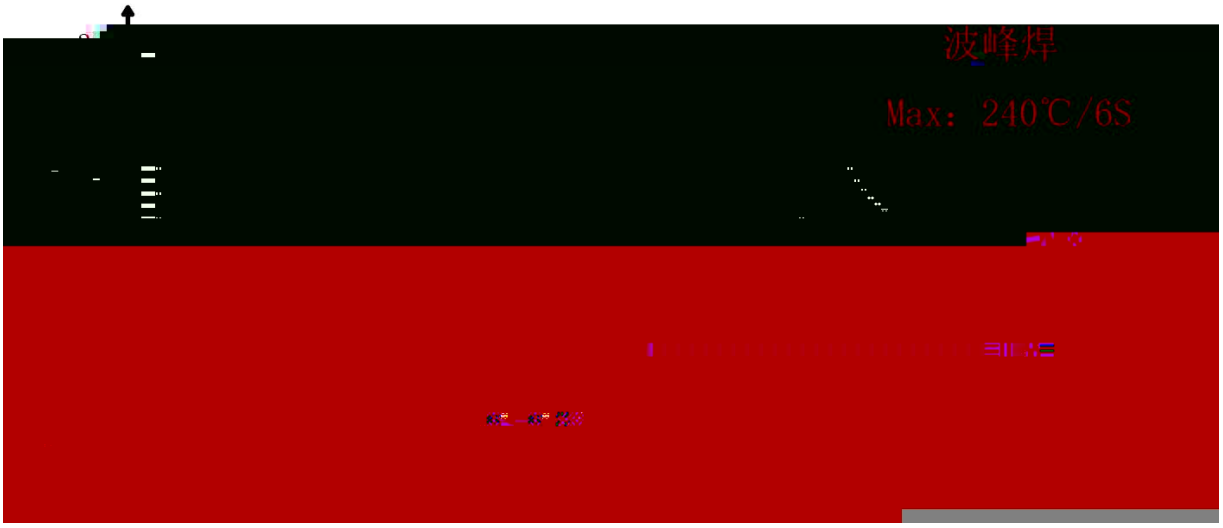


(Note)

包装

焊接指导

The wave peak welding curve is recommended :



Note

1

Lead solder temperature profile

2

Suggest one wave soldering frequency

3 LED

When soldering, do not put stress on the LED during heating

4

After soldering, do not warp the circuit board

5 240 /6S

The recommended maximum welding temperature for the product is 240 /6s

使用注意事項（1）

Moisture proof and anti-electrostatic package with moisture absorbent material is used, to keep moisture to a minimum.

30 60%RH

Before opening the package, the product should be kept at 30 or less and humidity less than 60% RH, and be used within a year.

30 40%RH 168 7

30 60%RH

After opening the package, the product should be stored at 30 or less and humidity less than 40%RH, and be soldered within 168 hours (7 days). It is recommended that the product be operated at the workshop condition of 30 and humidity less than 60%RH.

LED

5 24 0‘ €Đ À

If the moisture absorbent material has

使用注意事项（2）

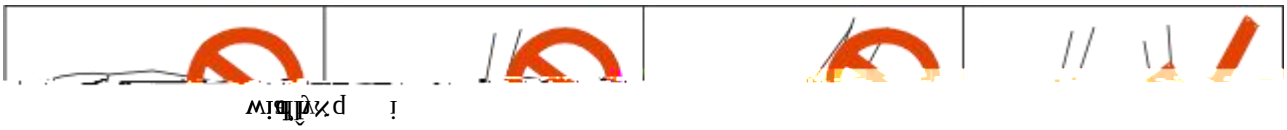
Precautions (2)

使用注意事项（3）

Precautions (3)

4、其他事项：

When handling the product, touching the encapsulant with bare hands will not only contaminate its surface, but also affect on its optical characteristics. Excessive force to the encapsulant might result in catastrophic failure of the LEDs due to die breakage or wire deformation. For this reason, please do not put excessive stress on LEDs, especially when the LEDs are heated such as during Reflow Soldering.



LED

The epoxy resin of encapsulant is fragile, so please avoid scratch or friction over the epoxy resin surface. While handling the product with tweezers, do not hold by the epoxy resin, be careful.